These assemblies are ESD sensitive. ESD precautions shall be observed.
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
These assemblies must comply with workstation standards IPC-A-610 Class 2, unless otherwise specified.
Place SH-J1 on J1 and SH-J2 on J2 (pins 1-2) and SH-J3 to SH-J4 on J3, SH-J5 to SH-J6 (pins 1-2)
Component ELI must be assembled to U3 before U3 is attached to the board.
Remove protective coverings from BLI and U3.
Slide pins of U3 into holes of ELI. ELI must lie flat on the back of U3.
Solder U3 - ELI assembly to the board.
Solder pins 1, 2, 3, 18, 19, and 20 of U3 to ELI from the top to insure electrical continuity.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: ISE4024</th>
<th>REV: E2</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TIDA-00373</td>
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PLOT NAME = Top Assembly Drawing
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Tッド INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
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